

2SK2607

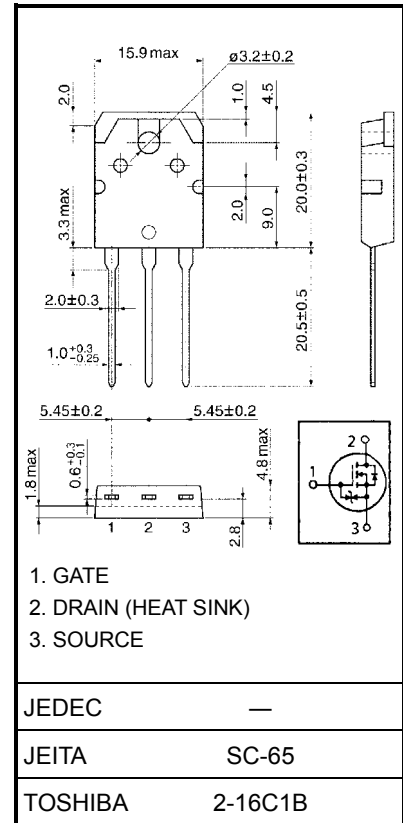
Chopper Regulator, DC-DC Converter and Moter Drive Applications

Unit: mm

- Low drain-source ON resistance : $R_{DS(ON)} = 1.0 \Omega$ (typ.)
- High forward transfer admittance : $|Y_{fs}| = 7.0 S$ (typ.)
- Low leakage current : $I_{DSS} = 100 \mu A$ (max) ($V_{DS} = 640 V$)
- Enhancement-mode : $V_{th} = 2.0 \sim 4.0 V$ ($V_{DS} = 10 V, I_D = 1 mA$)

Maximum Ratings ($T_a = 25^\circ C$)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	800	V
Drain-gate voltage ($R_{GS} = 20 k\Omega$)		V_{DGR}	800	V
Gate-source voltage		V_{GSS}	± 30	V
Drain current	DC (Note 1)	I_D	9	A
	Pulse (Note 1)	I_{DP}	27	
Drain power dissipation ($T_c = 25^\circ C$)		P_D	150	W
Single pulse avalanche energy (Note 2)		E_{AS}	778	mJ
Avalanche current		I_{AR}	9	A
Repetitive avalanche energy (Note 3)		E_{AR}	15	mJ
Channel temperature		T_{ch}	150	$^\circ C$
Storage temperature range		T_{stg}	-55~150	$^\circ C$



Weight: 4.6 g (typ.)

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	0.883	$^\circ C / W$
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	50	$^\circ C / W$

Note 1: Please use devices on condition that the channel temperature is below $150^\circ C$.

Note 2: $V_{DD} = 90 V, T_{ch} = 25^\circ C$ (initial), $L = 17.4 mH, R_G = 25 \Omega, I_{AR} = 9 A$

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.
Please handle with caution.

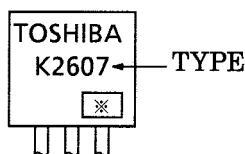
Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 30\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 10	μA
Gate-source breakdown voltage		$V_{(BR)GSS}$	$I_G = \pm 10\ \mu\text{A}, V_{DS} = 0\text{ V}$	± 30	—	—	V
Drain cut-off current		I_{DSS}	$V_{DS} = 640\text{ V}, V_{GS} = 0\text{ V}$	—	—	100	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	800	—	—	V
Gate threshold voltage		V_{th}	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	2.0	—	4.0	V
Drain-source ON resistance		$R_{DS(ON)}$	$V_{GS} = 10\text{ V}, I_D = 4\text{ A}$,	—	1.0	1.2	Ω
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 15\text{ V}, I_D = 4\text{ A}$	3.0	7.0	—	S
Input capacitance		C_{iss}	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	2160	—	pF
Reverse transfer capacitance		C_{rss}		—	45	—	
Output capacitance		C_{oss}		—	200	—	
Switching time	Rise time	t_r		—	25	—	ns
	Turn-on time	t_{on}		—	60	—	
	Fall time	t_f		—	25	—	
	Turn-off time	t_{off}		—	110	—	
Total gate charge (gate-source plus gate-drain)		Q_g	$V_{DD} \approx 400\text{ V}, V_{GS} = 10\text{ V}, I_D = 9\text{ A}$	—	68	—	nC
Gate-source charge		Q_{gs}		—	38	—	
Gate-drain ("miller") Charge		Q_{gd}		—	30	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	9	A
Pulse drain reverse current (Note 1)	I_{DRP}	—	—	—	27	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 9\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.9	V
Reverse recovery time	t_{rr}	$I_{DR} = 9\text{ A}, V_{GS} = 0\text{ V}, dI_{DR} / dt = 100\text{ A} / \mu\text{s}$	—	1000	—	ns
Reverse recovery charge	Q_{rr}		—	12	—	μC

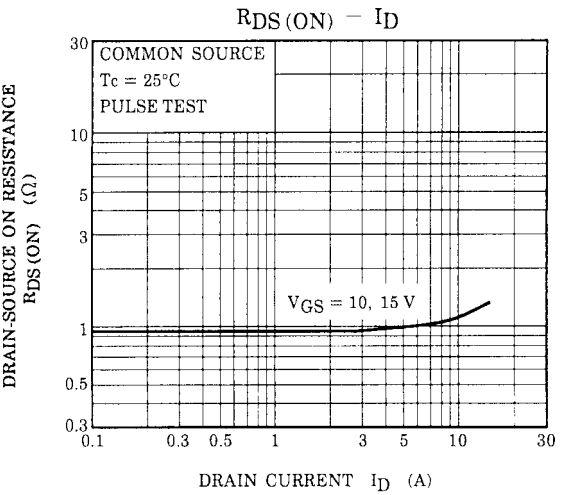
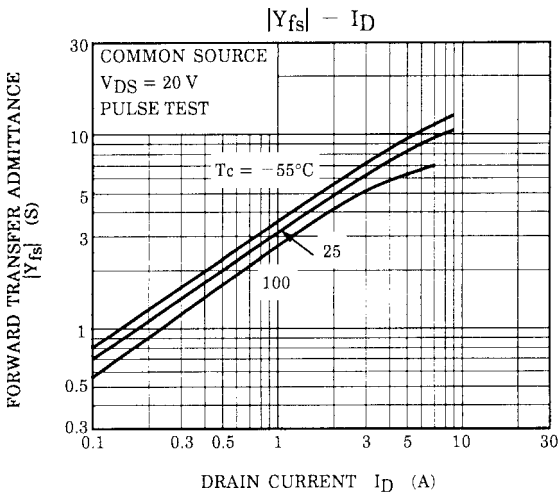
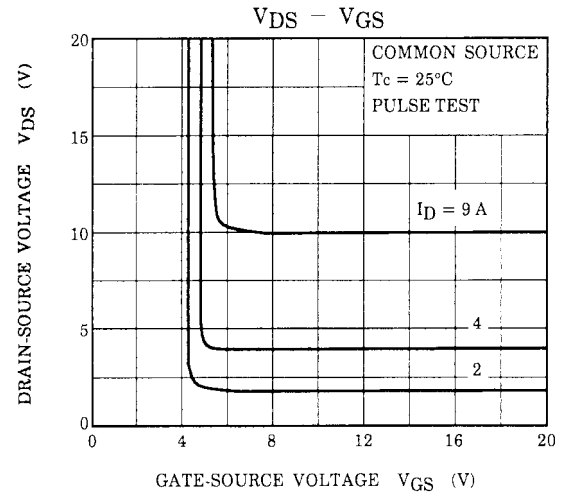
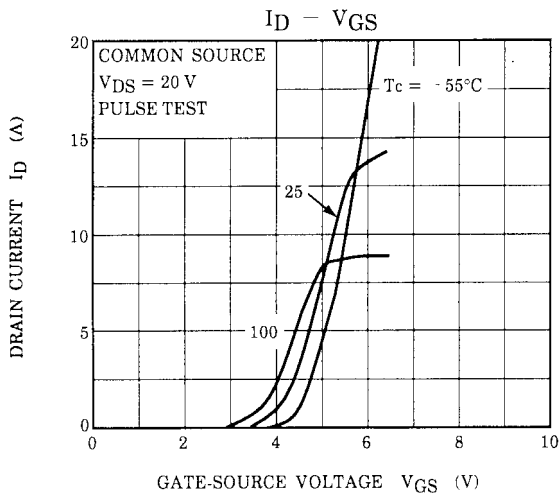
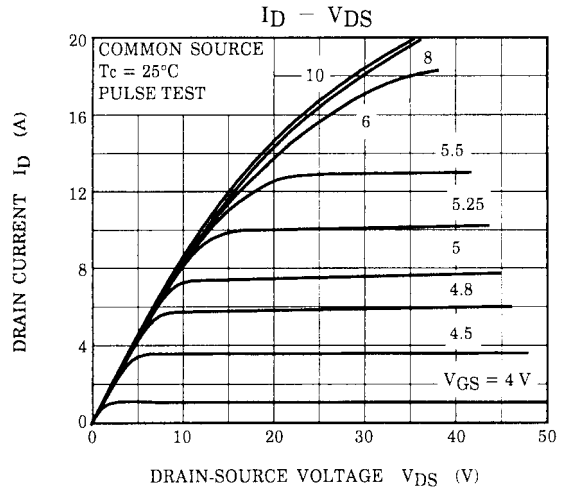
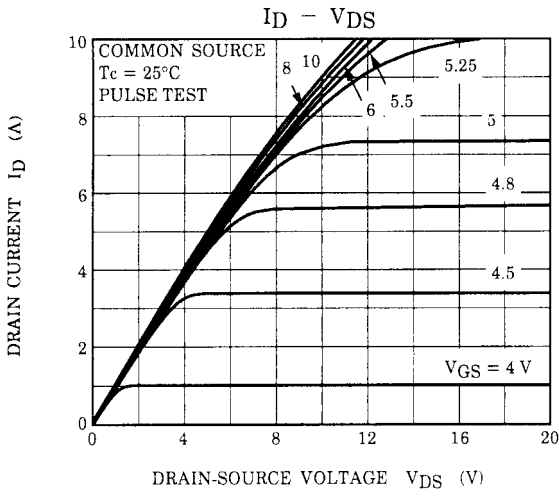
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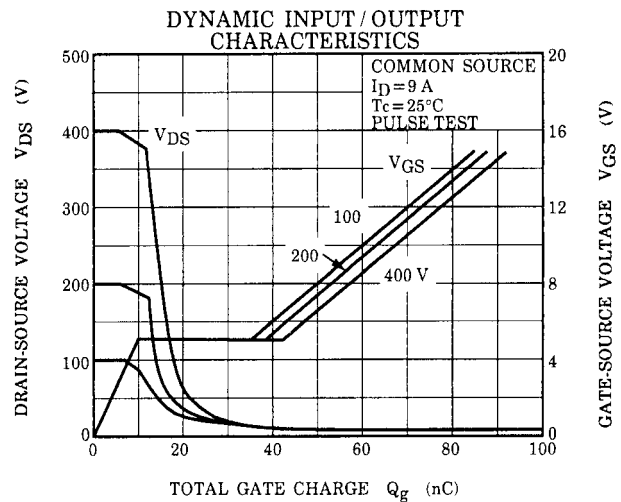
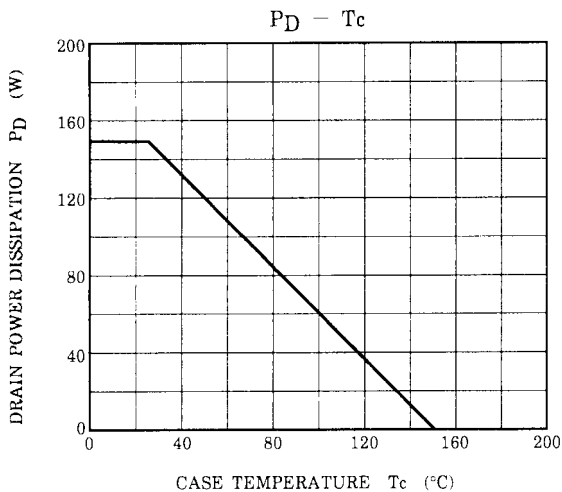
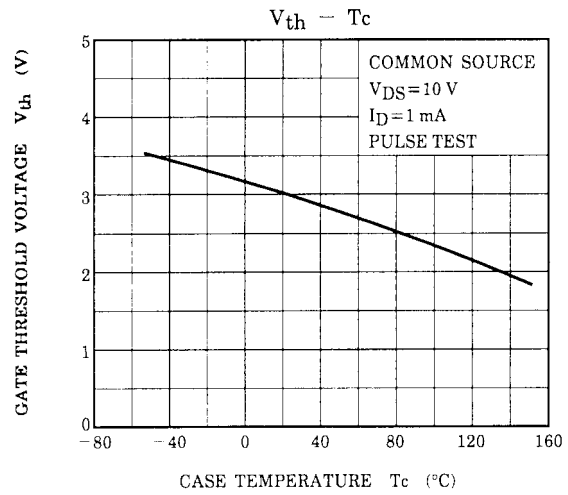
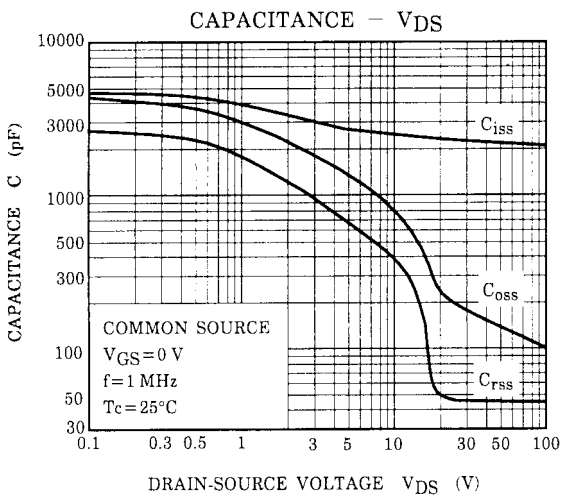
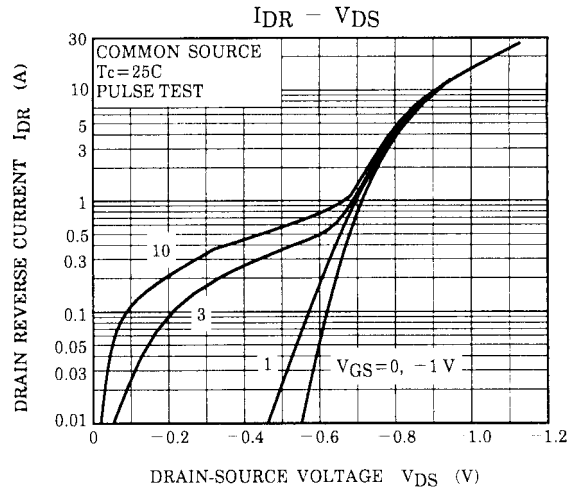
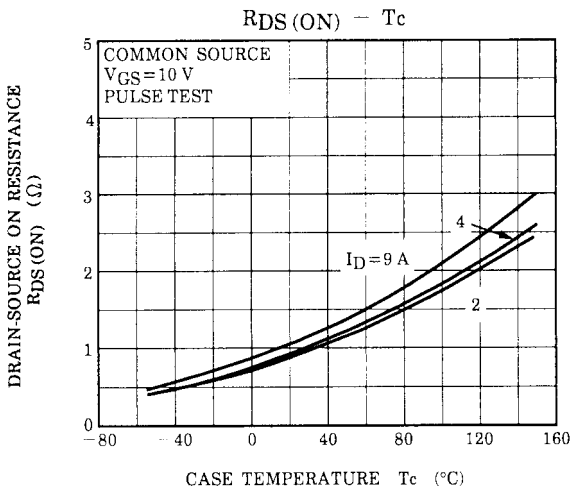


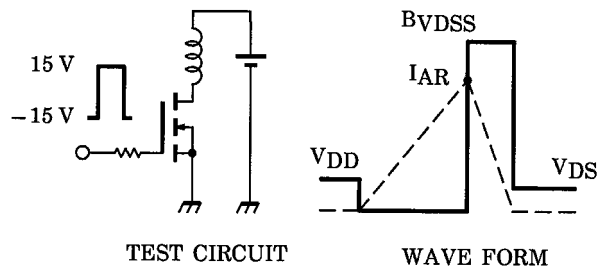
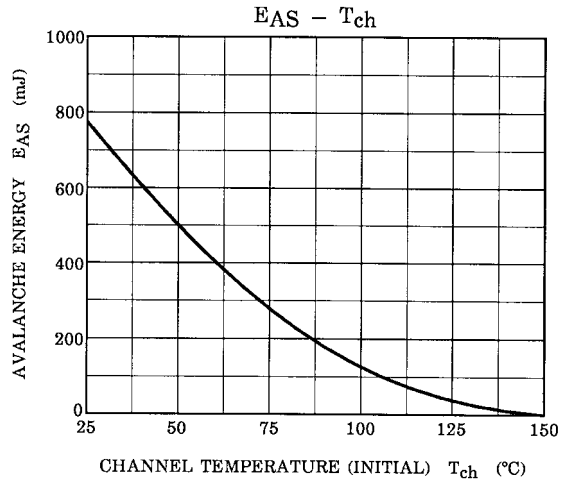
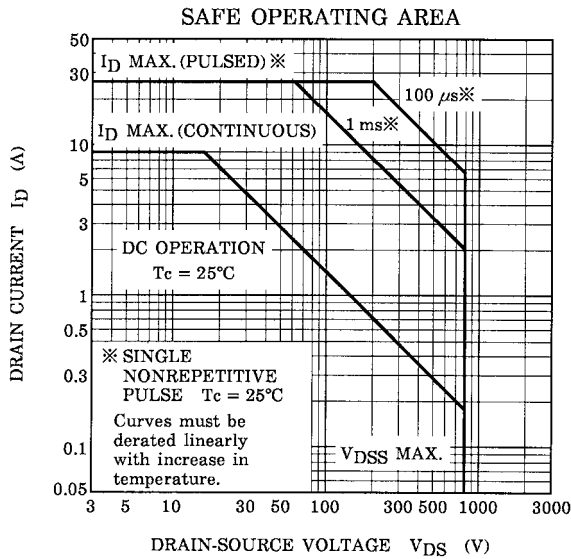
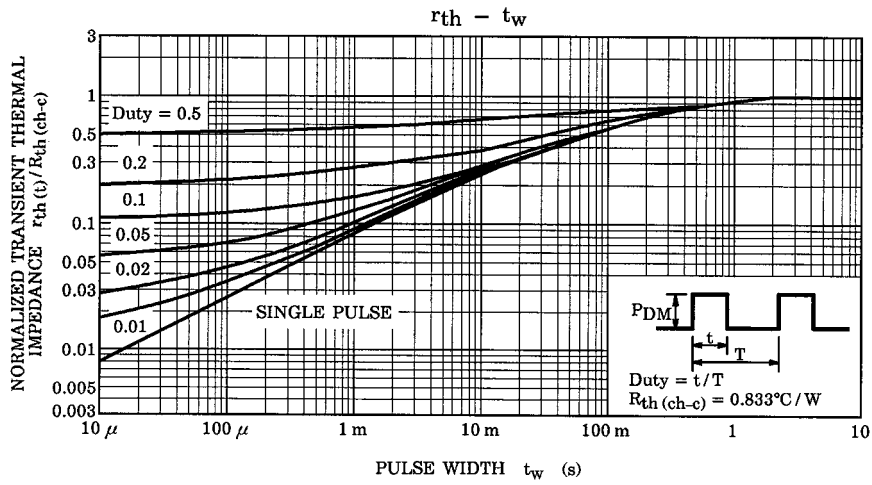
※ Lot Number

□ □ — Month (Starting from Alphabet A)

— Year (Last Number of the Christian Era)







$R_G = 25 \Omega$
 $V_{DD} = 90 \text{ V}, L = 17.4 \text{ mH}$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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